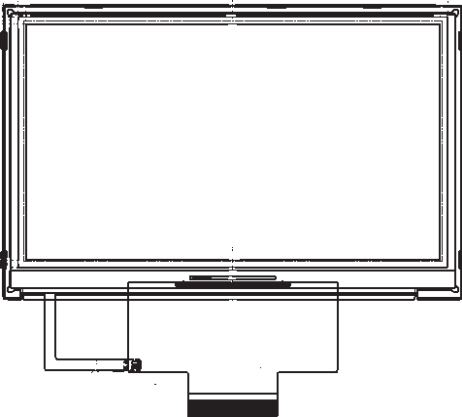




PRODUCT SPECIFICATION

# HDA430M

4.3', 480x3x272 TFT MONOCHROME GRAPHICS  
LCD DISPLAY MODULE



HANTRONIX, INC. 10080 BUBB RD. CUPERTINO, CA 95014	Q.A.:	REV.:	HDA430M	SHEET 1 OF 15
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## 1. GENERAL INFORMATION

Item	Contents	Unit
LCD Type	TFT TRANSMISSIVE	/
Viewing direction	12:00	O' Clock
Module Size (WX H)	105.5-67.2	mm <sup>2</sup>
Active area (WXH)	95.04-53.86	mm <sup>2</sup>
Number of Dots	480*3*272	/
Driver IC	ILI6480/NT39024	/
Colors	Monochrome	/
Backlight type	LED	/
Interface Type	24-bits RGB	/
Operating voltage	3.3	V
Surface luminance	450	cd/m <sup>2</sup>

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### 3.ABSOLUTE MAXIMUM RATINGS

Logic supply voltage, VDDIO	-0.5 to +5V
Analog supply voltage, AVDD	-0.3 to +7.0V
VGL	-16 to 0.3V
VGH~VGL	-0.3 to 35V

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of this device at these or any other conditions above those indicated in the operational sections of this specification is not implied and exposed to absolute maximum rating conditions for extended periods may affect device reliability.

### 4.ELECTRICAL SPECIFICATION

Item	Input/Output	Symbol	MIN	TYP	MAX	Unit	Remarks
TFT gate on voltage	VGH	VGH	+10	-	+16	V	
TFT gate off voltage	VGL	VGL	-16	-	-9	V	
TFT common electrode voltage	VCOMH	VCOMH	+2.5	-	+5	V	
	VCOML	VCOML	-2.5	-	0	V	

- Note: (1) Vcom must be adjusted to optimize display:cross\_talk,contrast ratio and etc.  
 (2) VGH is TFT gate operating voltage.  
 (3) VGL is TFT gate operating voltage.  
 The storage capacitance structure of this product is Cs on common.  
 (4) Environmental condition:25±5°C.  
 (5) TFT frame frequency advise 60HZ.

### 5. BACKLIGHT CHARACTERISTICS

Item	Symbol	min.	typ.	max.	Unit	Condition
Forward Voltage	Vf	18.6	19.8	21.0	V	1. IF = 20 mA/LED 2.Aperture:1°,12 Point 3.The Measurement instrument is:BM-7 4.Average=min/max*100%
Reverse Current	Ir			15	μA	
Luminance	Lv	5200			cd/m <sup>2</sup>	
Average		75			%	
Colour Coordinate	X	0.245		0.295		
	Y	0.245		0.295		

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## 6.AC CHARACTERISTICS

AC Electrical Characteristics (VDDIO=VDD=3.0 to 3.6v, GND=0V, TA=-20 to +85 °C)

Parameters	Symbol	Min.	Typ.	Max.	Unit	Conditions
<b>System operation timing</b>						
VDD power source slew time	TPOR	-	-	20	ms	From 0V to 99% VDD
GRB pulse width	tRSTW	10	50	-	us	R=10Kohm, C=1uF
<b>Input Output timing</b>						
DCLK clock time	Tclk	33.3	-	-	ns	DCLK=30MHz
DCLK clock low period	Towl	40	-	60	%	
DCLK clock high period	Towh	40	-	60	%	
Clock rising time	Trck	9	-	-	ns	
Clock falling time	Tfck	9	-	-	ns	
HSD width	Thwh	1	-	-	DCLK	
HSD period time	Th	55	60	65	us	
HSD setup time	Thsu	12	-	-	ns	
HSD hold time	Thhd	12	-	-	ns	
VSD width	Tvwh	1	-	-	Th	
VSD setup time	Tvsu	12	-	-	ns	
VSD hold time	Tvhd	12	-	-	ns	
Data setup time	Tdasu	12	-	-	ns	
Data hold time	Tdahd	12	-	-	ns	
DE setup time	Tdesu	12	-	-	ns	
DE hold time	Tdehd	12	-	-	ns	
Source output setting time	Tsst	-	-	12	us	10% to 90% CL=60pF, RL=2Kohm
Gate output setting time	Tgst	-	-	1200	ns	10% to 90%, CL=60pF
VCOM output setting time	Tcost	-	-	12	us	10% to 90%, CL=40nF, RL=50ohm
Time from VSD to 1st line data input	Tvs	3	8	31	Th	HV mode By HDL[4:0] setting

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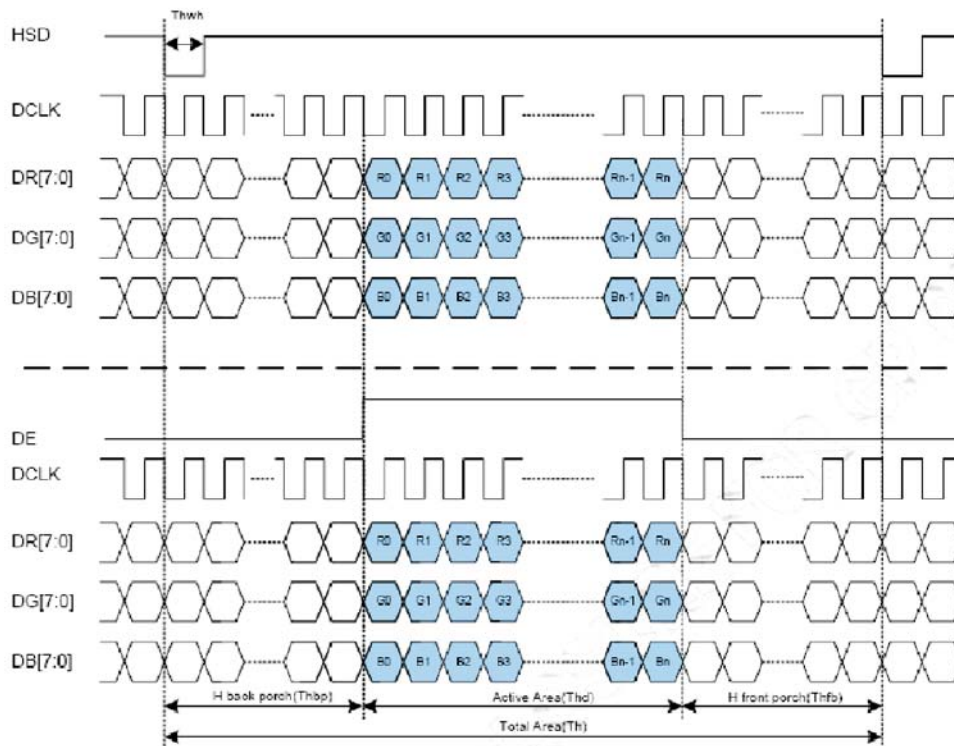
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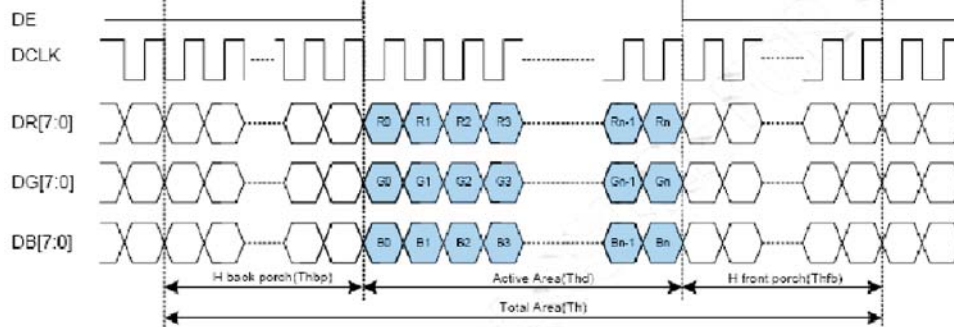


## Parallel RGB Mode Data format

(HV Mode)



(DE Mode)



## Parallel RGB input timign table

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
DCLK frequency	fclk	5	9	12	MHz
VSD period time	$T_v$	277	288	400	H
VSD display area	$T_{vd}$	272			H
VSD back porch	$T_{vb}$	3	8	31	H
VSD front porch	$T_{vfp}$	2	8	97	H
HSD period time	$T_h$	520	525	800	DCLK
HSD display area	$T_{hd}$	480			DCLK
HSD back porch	$T_{hbp}$	36	40	255	DCLK
HSD front porch	$T_{hfp}$	4	5	65	DCLK

## 7. OPTICAL CHARACTERISTICS

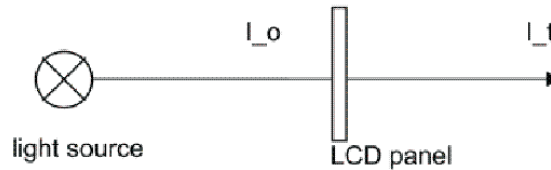
### Parameters and specifications

Item	Symbol	Specifications			Unit	Note
		Min.	Typ.	Max.		
Transmittance (Without Polarizer)	T%	-	45	-	%	Here the transmittance and response time are design value. <b>Reference Only</b>
Contrast ratio	Cr ( $\Theta=0^\circ$ )	400	550	-		
Response time (25°C)	$T_r + T_f$	-	45	-	ms	
Viewing angle ( $Cr \geq 100$ )	$\Theta_{21}$	-	60	-	deg	
	$\Theta_{22}$	-	60	-		
	$\Theta_{12}$	-	60	-		
	$\Theta_{11}$	-	60	-		

### Definitions and measuring methods

#### [1] Transmittance (T%)

The transmittance of the panel including polarizers is measured without electrical driving.



The Transmittance is defined as:

$$Tr = \frac{I_t}{I_o} \times 100\%$$

here,

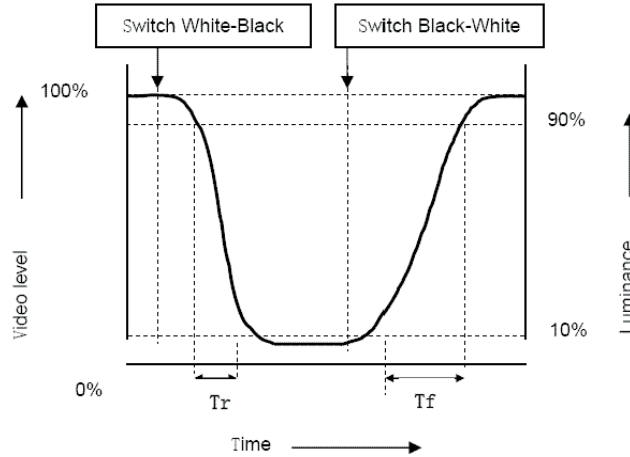
$I_o$ : the brightness of the light source.

$I_t$ : the brightness after panel transmission.

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**[2] Response Time(Tr、 Tf)**

The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.

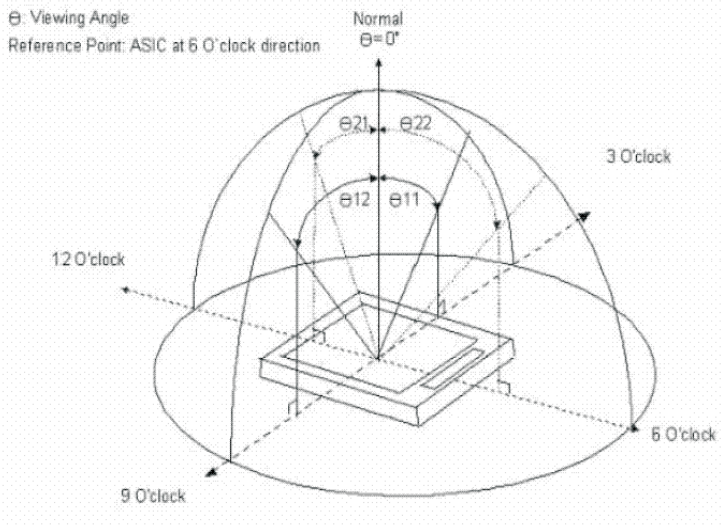


**[3] Contrast ratio (Cr)**

The contrast ratio (Cr), measured on a module, is the ratio between the luminance (L\_w) in a full white area (R=G=B=1) and the luminance (L\_d) in a dark area (R=G=B=0):

$$Cr = \frac{L_w}{L_d}$$

**[4]Viewing angle diagram**



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## 8.INTERFACE DESCRIPTION

Pin No.	Symbol	Description
1-2	VSS	Ground
3-4	DVDD	Power supply
5-28	DB0-DB23	Data bus
29	VSS	Ground
30	PCLK	Clock signal for data
31	DEN	Input data enable control
32	HSYNC	Horizontal sync
33	VSNC	Vertical sync
34-36	NC	No connection
37-38	A	LED power
39-40	K	LED power

## 9.APPLICATION CIRCUIT

Please consult our technical department for detail information.

## 10.INITIAL CODE

Please consult our technical department for detail information

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## 11. RELIABILITY TEST

No.	Test Item	Test Condition	Inspection after test
1	High Temperature Storage	80±2°C/200 hours	Inspection after 2~4hours storage at room temperature,the sample shall be free from defects: 1.Air bubble in the LCD; 2.Sealleak; 3.Non-display; 4.missing segments; 5.Glass crack; 6.Current Idd is twice higher than initial value.
2	Low Temperature Storage	-30±2°C/200 hours	
3	High Temperature Operating	70±2°C/120 hours	
4	Low Temperature Operating	-20±2°C/120 hours	
5	Temperature Cycle	-20 °C ~25~70 °C × 10cycles (30min.) (5min.) (30min.)	
6	Damp Proof Test	50°C ±5°C ×90%RH/120 hours	
7	Vibration Test	Frequency: 10Hz~55Hz~10Hz Amplitude: 1.5mm, X, Y, Z direction for total 3hours (Packing condition)	
8	Drooping test	Drop to the ground from 1m height, one time, every side of carton. (Packing condition)	
9	ESD test	Voltage: ±8KV R: 330Ω C: 150pF Air discharge, 10time	

**Remark:**

1. The test samples should be applied to only one test item.
2. Sample size for each test item is 5~10pcs.
3. For Damp Proof Test, Pure water(Resistance>10MΩ) should be used.
4. In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
5. EL evaluation should be excepted from reliability test with humidity and temperature:  
Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
6. Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.
7. Please use automatic switch menu(or roll menu) testing mode when test operating mode.

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This specification is made to be used as the standard acceptance/rejection criteria for Color mobile phone LCM.

### 1 Sample plan

Sampling plan according to GB/T2828.1-2003/ISO 2859-1: 1999 and ANSI/ASQC Z1.4-1993, normal level 2 and based on:

Major defect: AQL 0.65

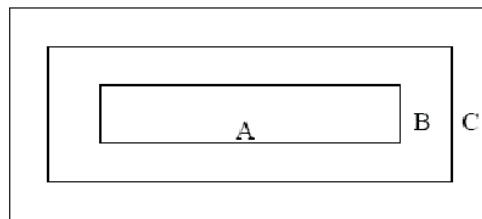
Minor defect: AQL 1.5

### 2. Inspection condition

Viewing distance for cosmetic inspection is about 30cm with bare eyes, and under an environment of 20~40W light intensity, all directions for inspecting the sample should be within

45° against perpendicular line.

### 3. Definition of inspection zone in LCD.



Zone A: character/Digit area

Zone B: viewing area except Zone A (ZoneA+ZoneB=minimum Viewing area)

Zone C: Outside viewing area (invisible area after assembly in customer's product)

Fig.1 Inspection zones in an LCD.

Note: As a general rule, visual defects in Zone C are permissible, when it is no trouble for quality and assembly of customer's product.

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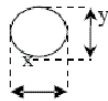
TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA

**4. Inspection standards**

**4.1 Major Defect**

Item No	Items to be inspected	Inspection Standard	Classification of defects
4.1.1	All functional defects	1) No display 2) Display abnormally 3) Missing vertical, horizontal segment 4) Short circuit 5) <del>Back-light no lighting, flickering and abnormal lighting.</del>	Major
4.1.2	Missing	Missing component	
4.1.3	Outline dimension	Overall outline dimension beyond the drawing is not allowed.	

**4.2 Cosmetic Defect**

Item No	Items to be inspected	Inspection Standard	Classification of defects																									
4.2.1	Clear Spots	For dark/white spot, size $\Phi$ is defined as $\Phi = (x+y)/2$ 	Minor																									
	Black and white Spot defect Pinhole, Foreign Particle, Dirt under polarizer	<p>1.</p> <table border="1"> <thead> <tr> <th rowspan="2">Zone Size(mm)</th> <th colspan="3">Acceptable Qty</th> </tr> <tr> <th>A</th> <th>B</th> <th>C</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.10</math></td> <td colspan="3">Ignore</td> </tr> <tr> <td><math>0.10 &lt; \Phi \leq 0.15</math></td> <td colspan="3">2</td> </tr> <tr> <td><math>0.15 &lt; \Phi \leq 0.20</math></td> <td colspan="3">1</td> </tr> <tr> <td><math>\Phi &gt; 0.20</math></td> <td colspan="3">0</td> </tr> </tbody> </table>		Zone Size(mm)	Acceptable Qty			A	B	C	$\Phi \leq 0.10$	Ignore			$0.10 < \Phi \leq 0.15$	2			$0.15 < \Phi \leq 0.20$	1			$\Phi > 0.20$	0				
Zone Size(mm)	Acceptable Qty																											
	A	B	C																									
$\Phi \leq 0.10$	Ignore																											
$0.10 < \Phi \leq 0.15$	2																											
$0.15 < \Phi \leq 0.20$	1																											
$\Phi > 0.20$	0																											
4.2.1	Dim Spots	2.	Minor																									
	Circle shaped and dim edged defects	<table border="1"> <thead> <tr> <th rowspan="2">2. Zone Size(mm)</th> <th colspan="3">Acceptable Qty</th> </tr> <tr> <th>A</th> <th>B</th> <th>C</th> </tr> </thead> <tbody> <tr> <td><math>\Phi \leq 0.2</math></td> <td colspan="3">Ignore</td> </tr> <tr> <td><math>0.20 &lt; \Phi \leq 0.40</math></td> <td colspan="3">3</td> </tr> <tr> <td><math>0.40 &lt; \Phi \leq 0.60</math></td> <td colspan="3">2</td> </tr> <tr> <td><math>0.60 &lt; \Phi \leq 0.80</math></td> <td colspan="3">1</td> </tr> <tr> <td><math>0.80 &lt; \Phi</math></td> <td colspan="3">0</td> </tr> </tbody> </table>		2. Zone Size(mm)	Acceptable Qty			A	B	C	$\Phi \leq 0.2$	Ignore			$0.20 < \Phi \leq 0.40$	3			$0.40 < \Phi \leq 0.60$	2			$0.60 < \Phi \leq 0.80$	1			$0.80 < \Phi$	0
2. Zone Size(mm)	Acceptable Qty																											
	A	B	C																									
$\Phi \leq 0.2$	Ignore																											
$0.20 < \Phi \leq 0.40$	3																											
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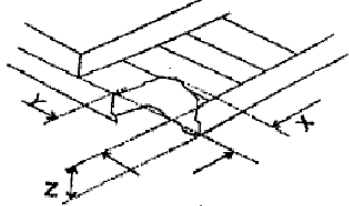
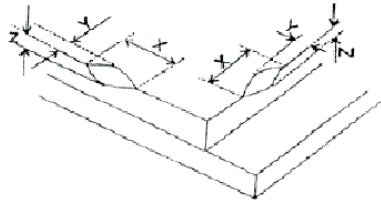
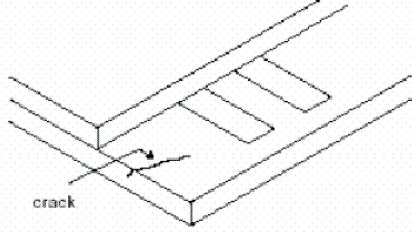
TITLE: FUNCTIONAL TEST & INSPECTION CRITERIA

4.2. Cosmetic Defect

Item No	Items to be inspected	Inspection Standard					Classification of defects
4.2.2	Line defect Black line, White line, Foreign material under polarizer,	Size(mm)		Acceptable Qty			Minor
		L(Length)	W(Width)	Zone			
				A	B	C	
		Ignore	$W \leq 0.02$	Ignore			
		$L \leq 3.0$	$0.02 < W \leq 0.03$	2			
		$L \leq 2.0$	$0.03 < W \leq 0.05$	1			
	$0.05 < W$	Define as spot defect					
4.2.3	Polarizer scratch	If the Polarizer scratch can be seen after mobile phone cover assembling or in the operating condition, judge by the line defect of 4.2.2. If the Polarizer scratch can be seen only in non-operating condition or some special angle, judge by the following.					Minor
		Size(mm)		Acceptable Qty			
		L(Length)	W(Width)	Zone			
				A	B	C	
		Ignore	$W \leq 0.03$	Ignore			
		$5.0 < L \leq 10.0$	$0.03 < W \leq 0.05$	2			
$L \leq 5.0$	$0.05 < W \leq 0.08$	1					
	$0.08 < W$	0					
4.2.4	Polarize Air bubble	Air bubbles between glass & polarizer					Minor
		Size(mm)	Acceptable Qty				
			A	B	C		
		$\Phi \leq 0.2$	Ignore				
		$0.20 < \Phi \leq 0.30$	2				
$0.30 < \Phi \leq 0.50$	1						
	$0.50 < \Phi$	0					

TITLE:FUNCTIONAL TEST & INSPECTION CRITERIA

4.3. Cosmetic Defect

Item No	Items to be inspected	Inspection Standard	Classification of defects						
4.3.5	Glass defect	<p>(i) Chips on corner</p>  <table border="1" data-bbox="537 695 1062 779"> <tr> <td>X</td> <td>Y</td> <td>Z</td> </tr> <tr> <td>≤2.0</td> <td>≤S</td> <td>Disregard</td> </tr> </table> <p>Notes: S=contact pad length Chips on the corner of terminal shall not be allowed to extend into the ITO pad or expose perimeter seal.</p>	X	Y	Z	≤2.0	≤S	Disregard	Minor
		X	Y	Z					
		≤2.0	≤S	Disregard					
<p>(ii) Usual surface cracks</p>  <table border="1" data-bbox="516 1142 1078 1226"> <tr> <td>X</td> <td>Y</td> <td>Z</td> </tr> <tr> <td>≤3.0</td> <td>&lt;Inner border line of the seal</td> <td>Disregard</td> </tr> </table>	X	Y	Z	≤3.0	<Inner border line of the seal	Disregard	Minor		
X	Y	Z							
≤3.0	<Inner border line of the seal	Disregard							
<p>(iii) Crack Cracks tend to break are not allowed.</p> 	Major								
4.3.6	Parts alignment	<p>1) Not allow IC and FPC/heat-seal lead width is more than 50% beyond lead pattern. 2) Not allow chip or solder component is off center more than 50% of the pad outline.</p>	Minor						
4.3.7	SMT	According to the <Acceptability of electronic assemblies> IPC-A-610C class 2 standard. Component missing or function defect are Major defect, the others are Minor defect.							

